

Title (en)  
IMPLANT DEVICE AND METHOD OF MAKING THE SAME

Title (de)  
IMPLANTATVORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)  
DISPOSITIF D'IMPLANT ET SON PROCÉDÉ DE FABRICATION

Publication  
**EP 3340929 A1 20180704 (EN)**

Application  
**EP 16842692 A 20160826**

Priority  
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Abstract (en)  
[origin: WO2017040302A1] The invention provides chip packaging and processes for the assembly of retinal prosthesis devices. Advantageously, photo-patternable adhesive or epoxy such as photoresist is used as glue to attach a chip to the targeted thin-film (e.g., parylene) substrate so that the chip is used as an attachment to prevent delamination.

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